



Material Composition

Product GS9068ACKAE3

genDOC ID: 54938.1

Package 8L SOIC

Manufacturer Gennum Corporation

Date

06/07/2009

Component	Subcomponent	Weight of Component mg	Substances	Weight of Substance mg	Homogeneous material	
					%	ppm
Leadframe	Olin 194FH	24.256	Cu	23.650	97.500	975000
			Fe	0.570	2.350	23500
			Zn	0.029	0.120	1200
			P	0.007	0.030	300
			Sub total			24.256
Mold cmpd	EME G600	48.295	SiO2	41.051	85.000	850000
			Epoxy resin	2.753	5.700	57000
			Epoxy/Creosol/Novolac	1.932	4.000	40000
			Phenol resin	2.415	5.000	50000
			Carbon black	0.145	0.300	3000
			Sub total			48.295
Chip		1.340	Si	1.332	99.400	994000
			Al	0.008	0.600	6000
Sub total			1.340	100.000		
Die Attach	CRM1076R	0.143	Ag	0.107	75.000	750000
			Epoxy Resin	0.036	25.000	250000
Sub total			0.143	100.000		
Wires	SGA3	0.214	Au	0.214	100.000	1000000
External Lead finish		1.334	Sn	1.334	100.000	1000000
Int. Lead finish		0.186	Ag	0.186	100.000	1000000
Weight total		75.768				

GENNUM CORPORATION

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